

NOVASTACK® 35-HDH

高度1.5 mm, 0.35 mm 间距, 全屏蔽式, 高背设计,
高速 40 Gbps (≒ 20 GHz)/通道传输

Product Specifications:

Board Pitch (mm)		0.35
Wiping Length (mm)		0.33
Mated Size (mm)	Height	1.5 +/- 0.10
	Width	3.3+(0.35*?p/2)
	Depth	3.64
Current Rating	Signal	0.5A/pin (12.0A Max. (Total))
	Power	-
Pin Counts	Range	10 - 70
	Available	60, 70

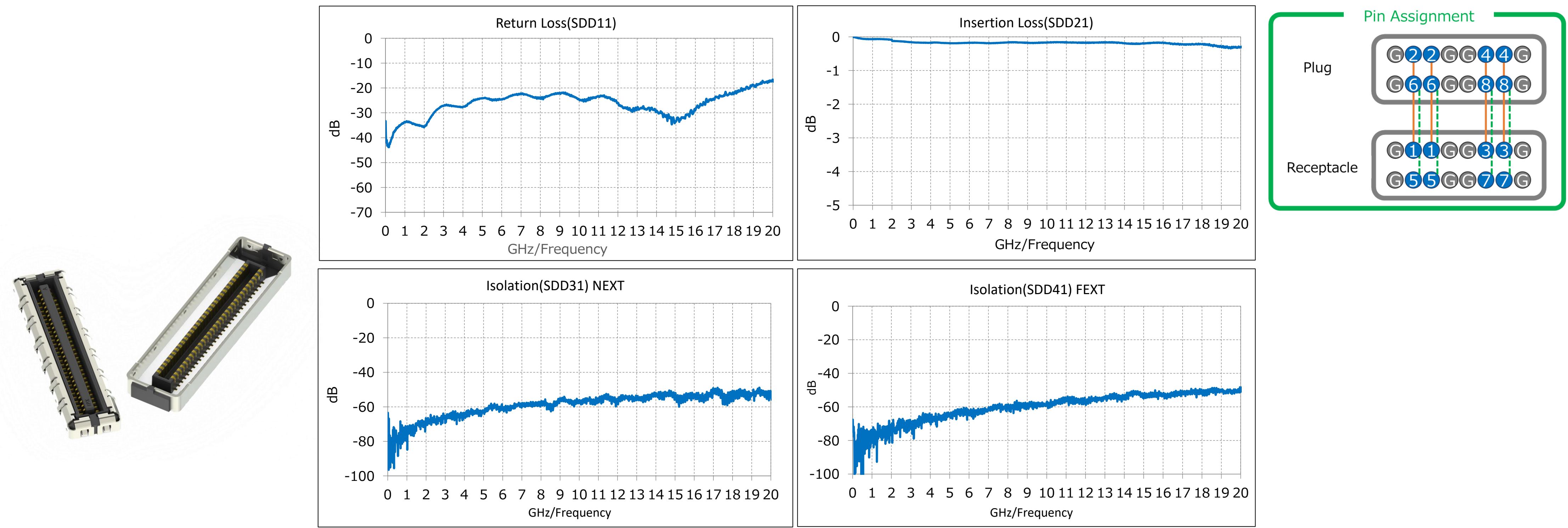
Applicable Standards (Reference Only):

USB4 (20 Gbps/lane); USB 3.1 Gen 2 (10 Gbps); eDP HBR 3 (8.1 Gbps); eDP HBR 2 (5.4 Gbps); HDMI 2.0 (6 Gbps); V-By-One HS 1.4 (4 Gbps); MiPi standards

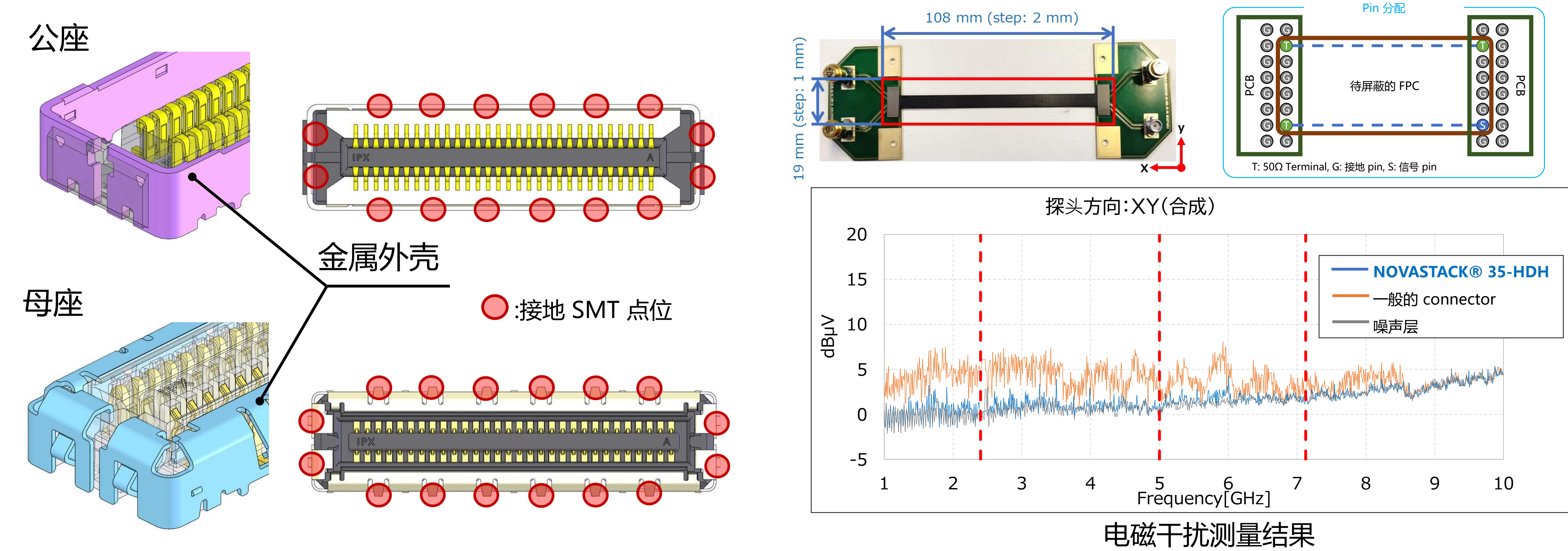
* 如需了解未列出或不在范围内的pin 数, 请联系我们。



支持 40 Gbps (≒ 20 GHz)/通道传输, 是最新高速信号的理想选择

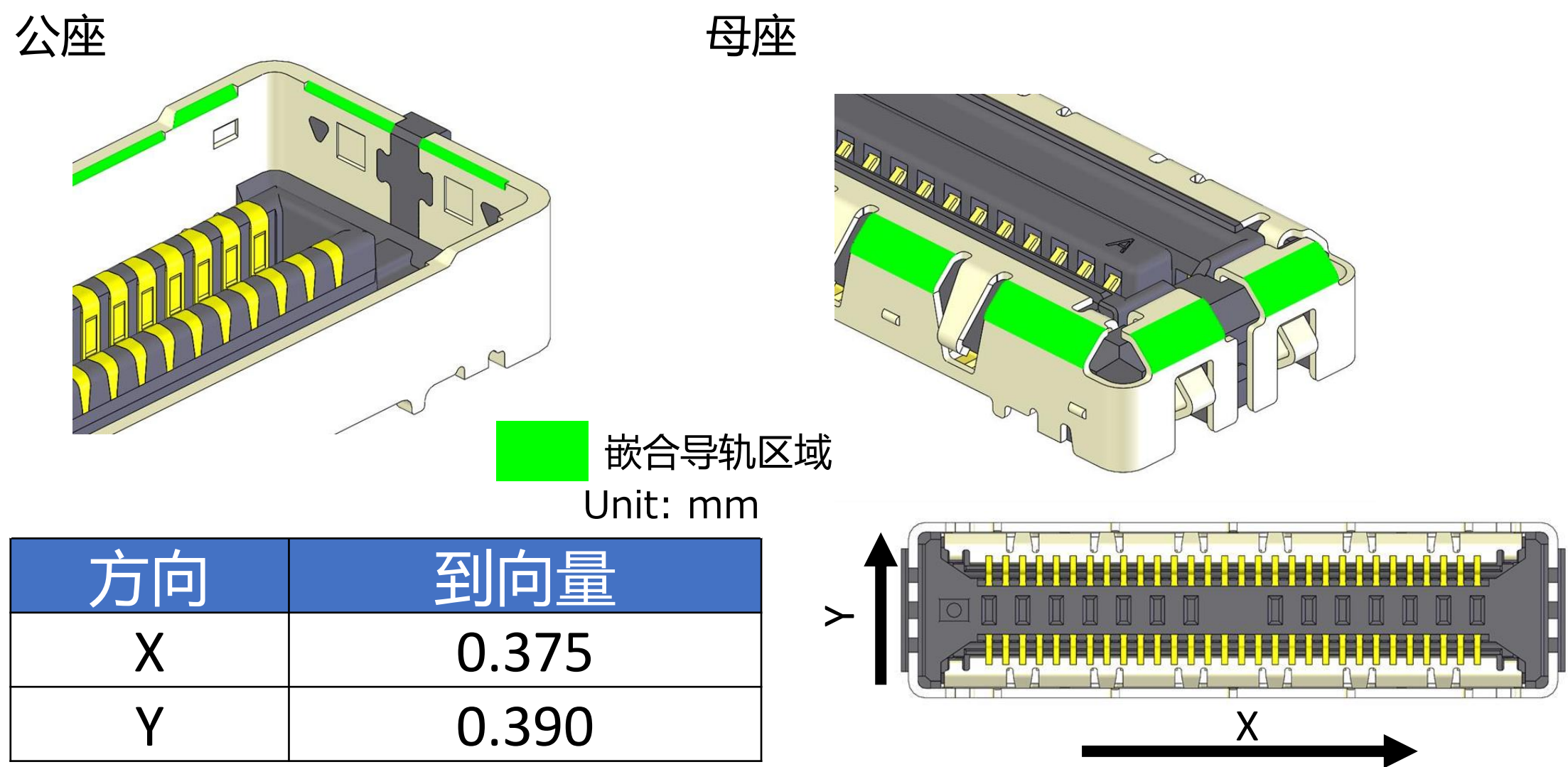


ZenShield® 全屏蔽和多点接地设计, 可防止 EMI 泄漏

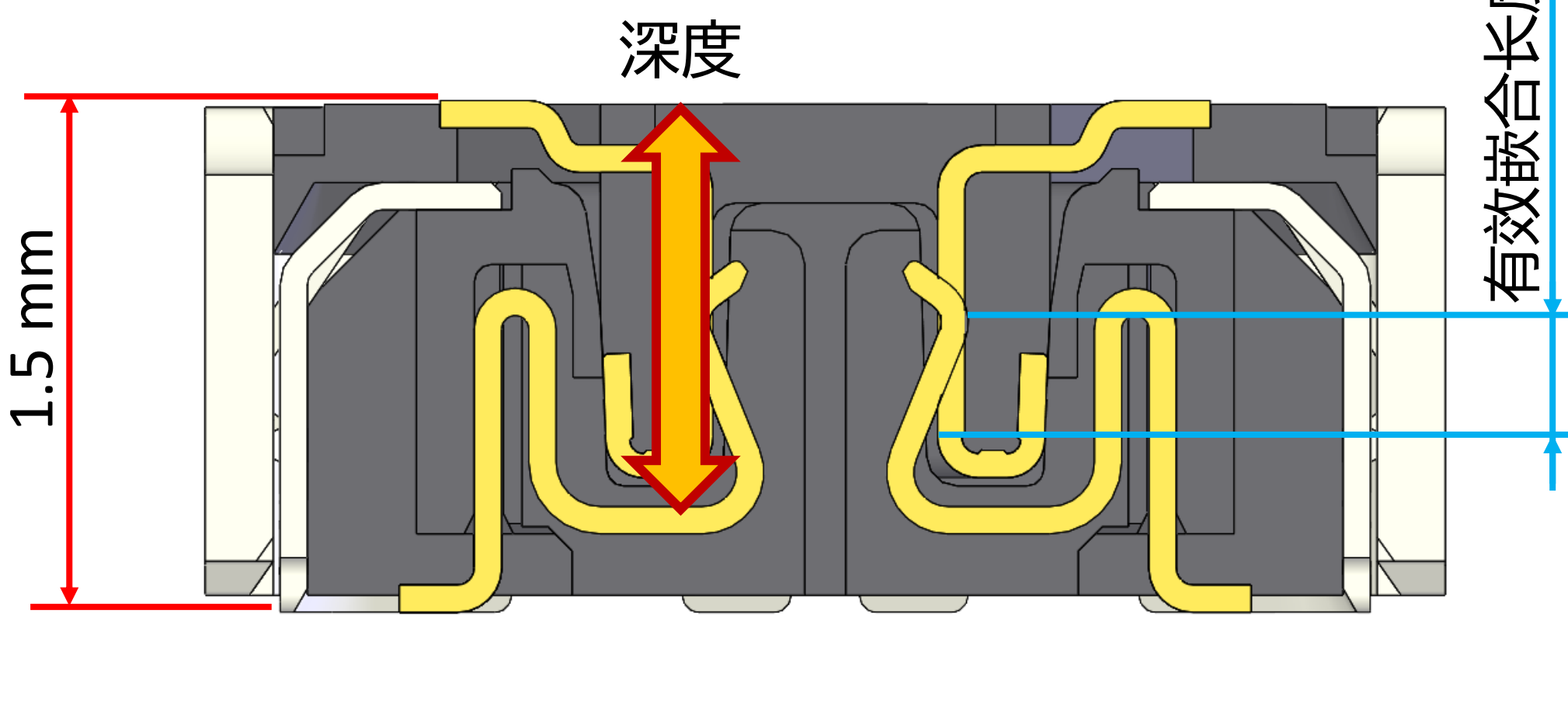


高背连接器设计, 具有出色的配接可加工性

导轨可实现正确位置的嵌合



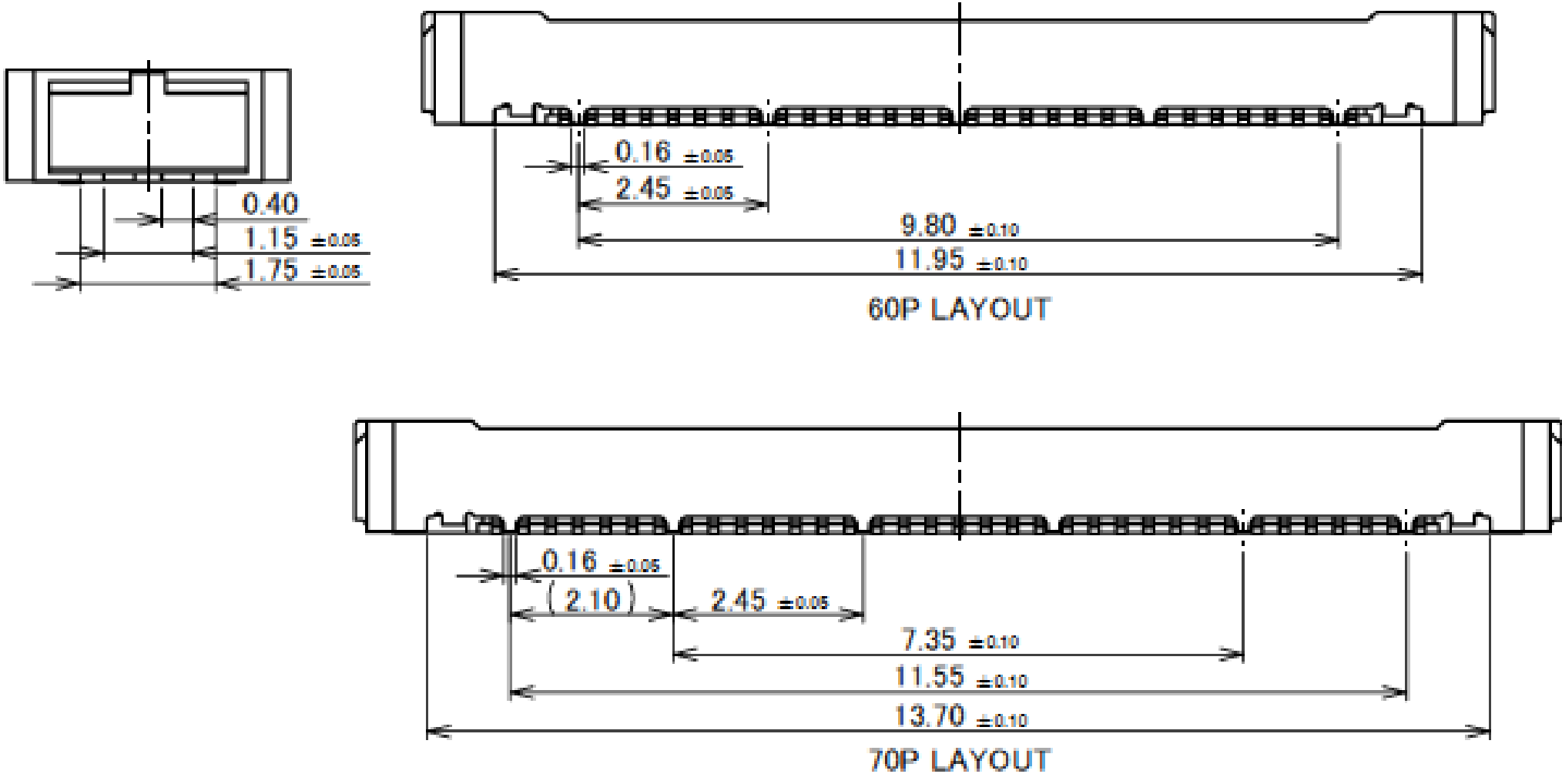
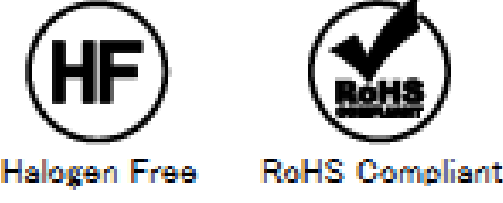
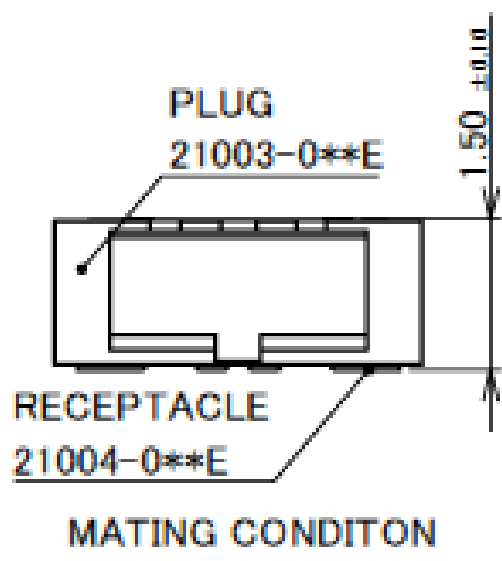
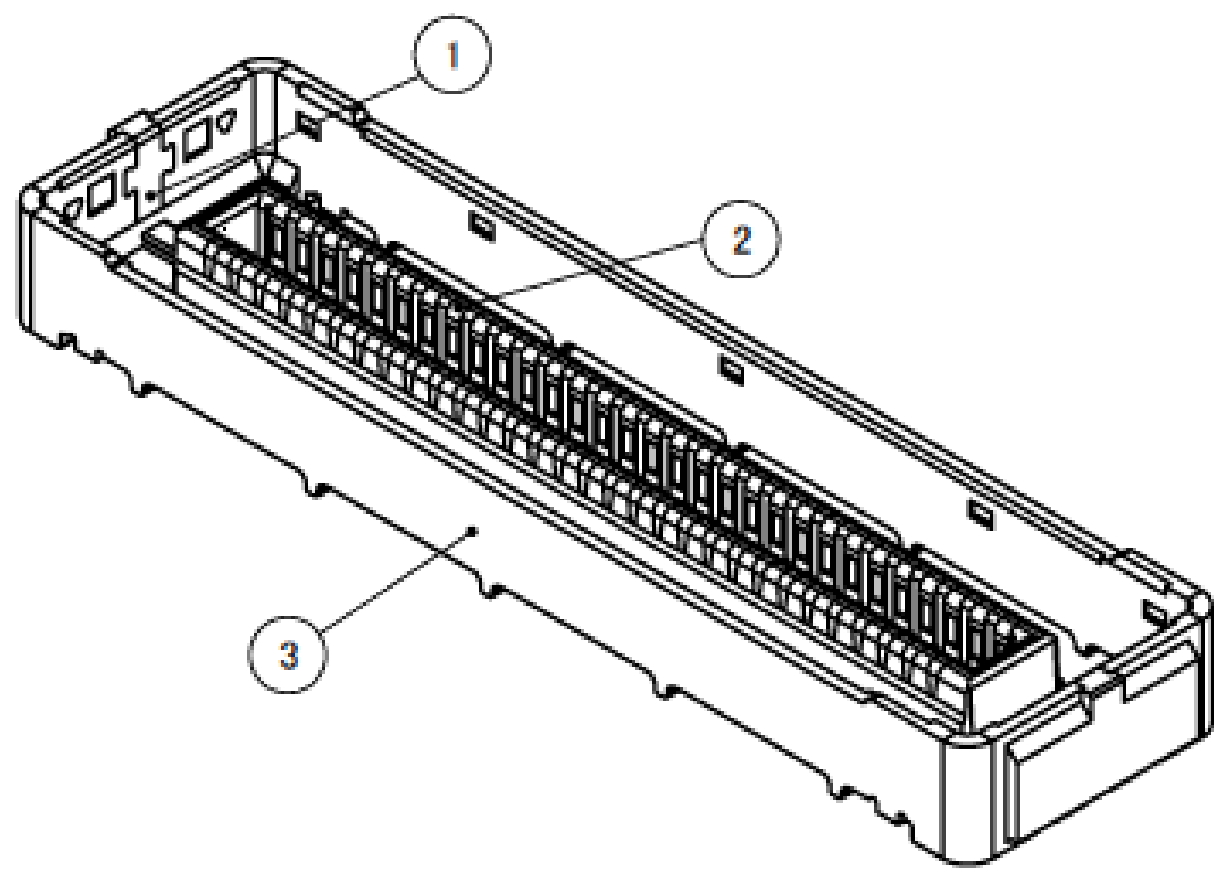
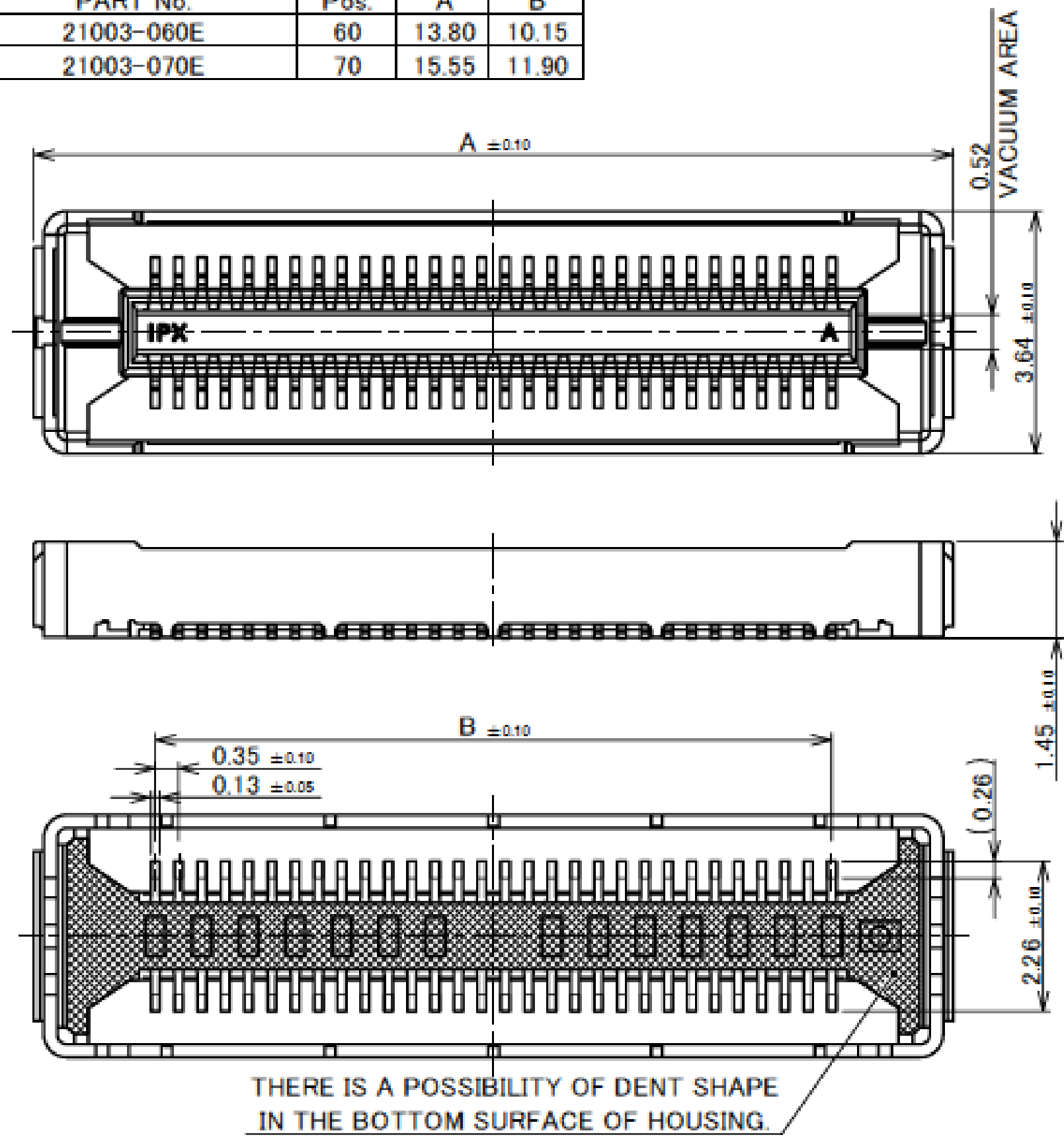
较长的嵌合长度可大大降低嵌合时发生倾斜的可能性



Component Parts Detail

Plug Assembly

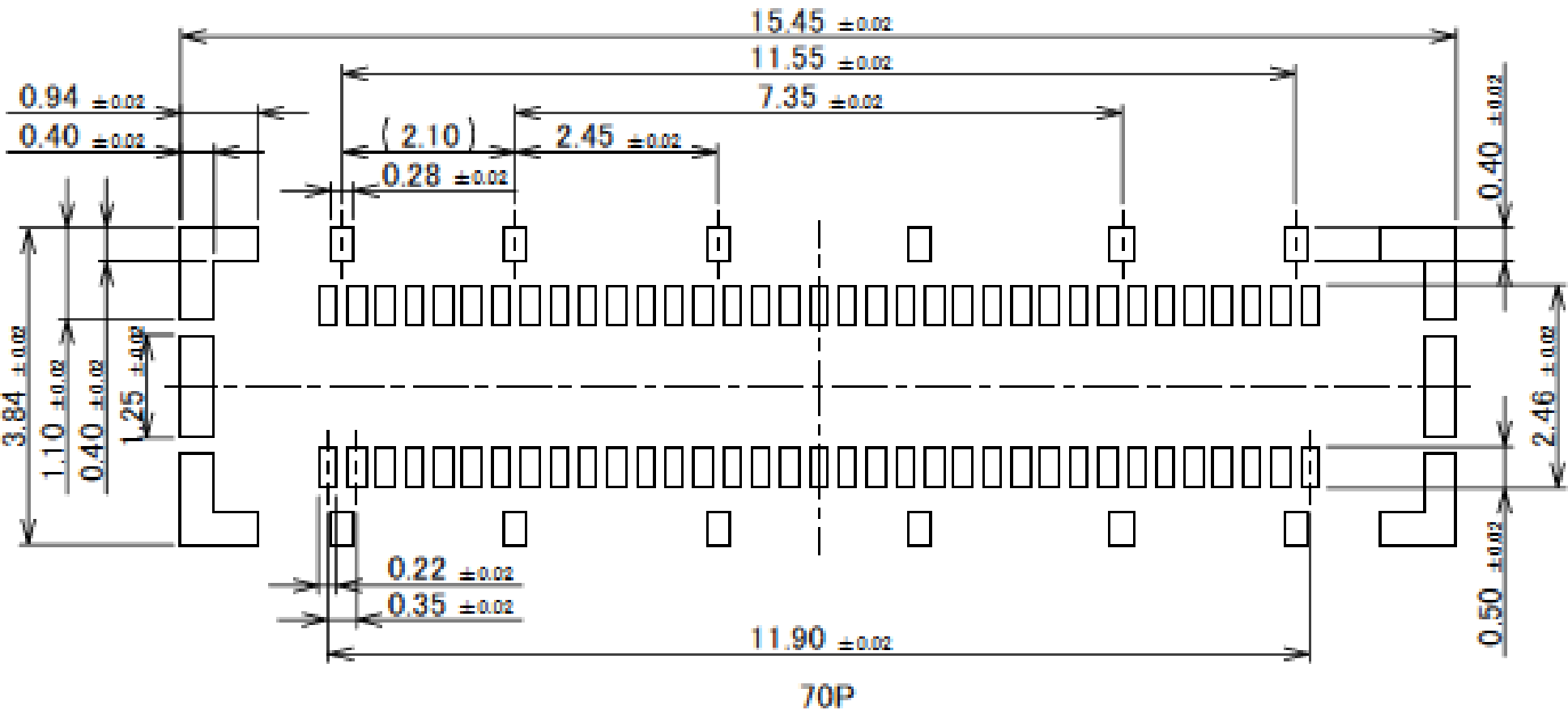
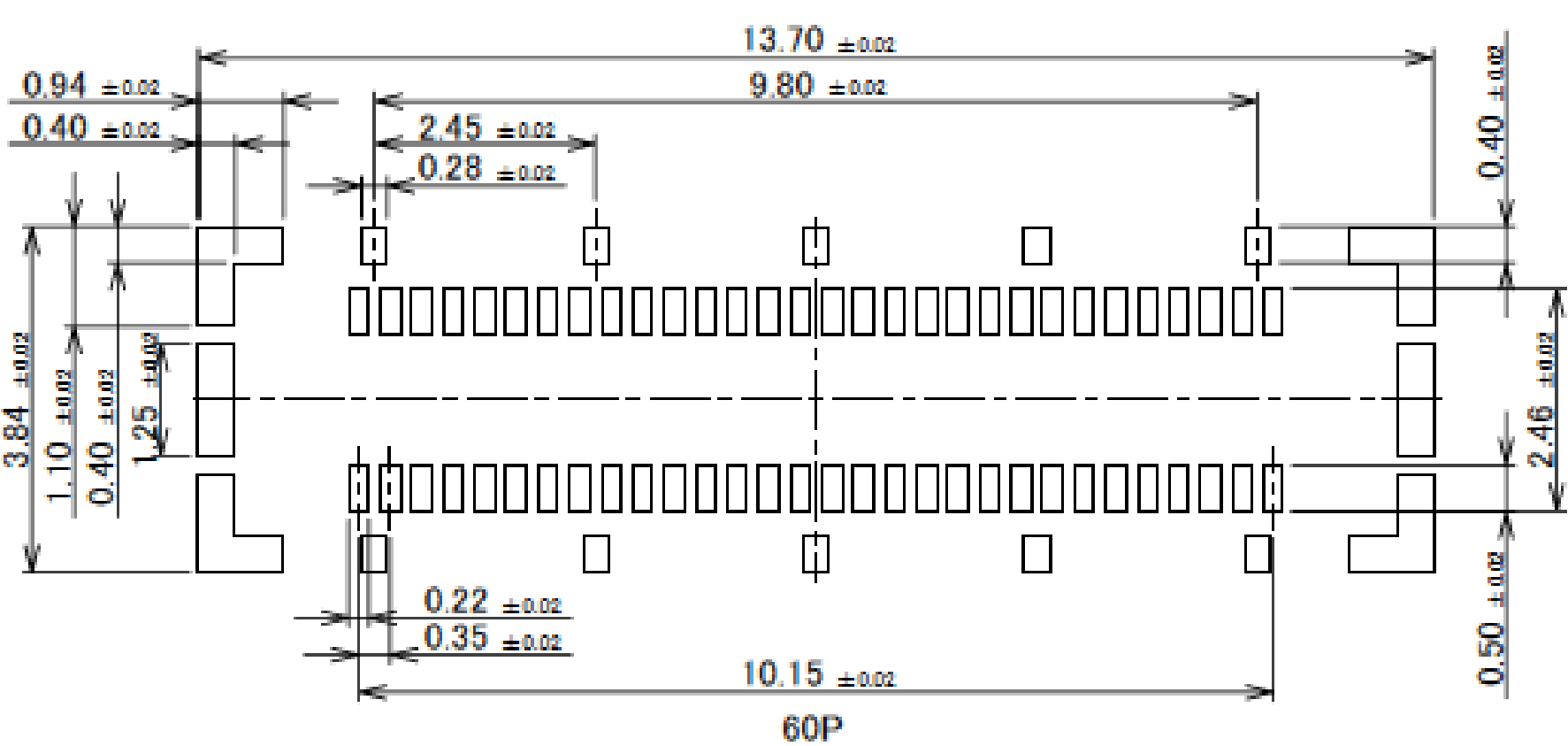
Recommended P/N		21003-0**E		
PART No.	Pos.	A	B	
21003-060E	60	13.80	10.15	
21003-070E	70	15.55	11.90	



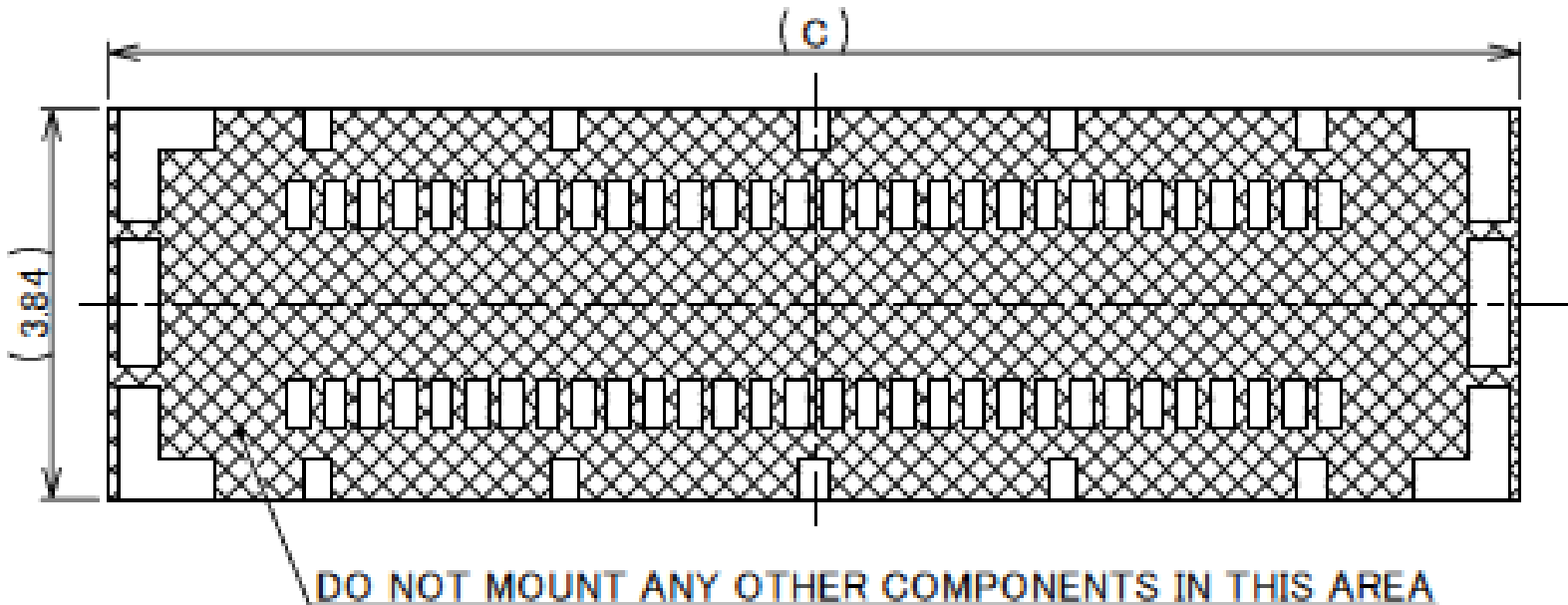
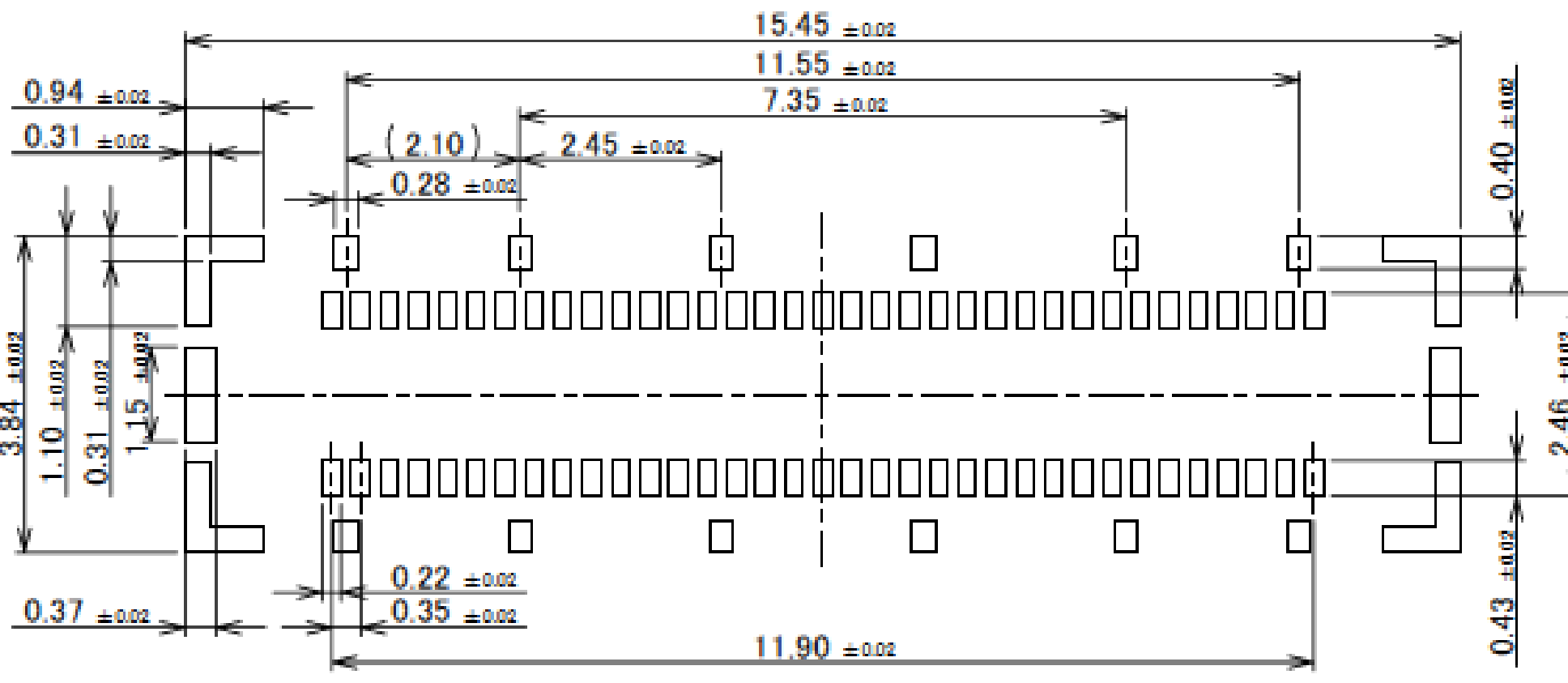
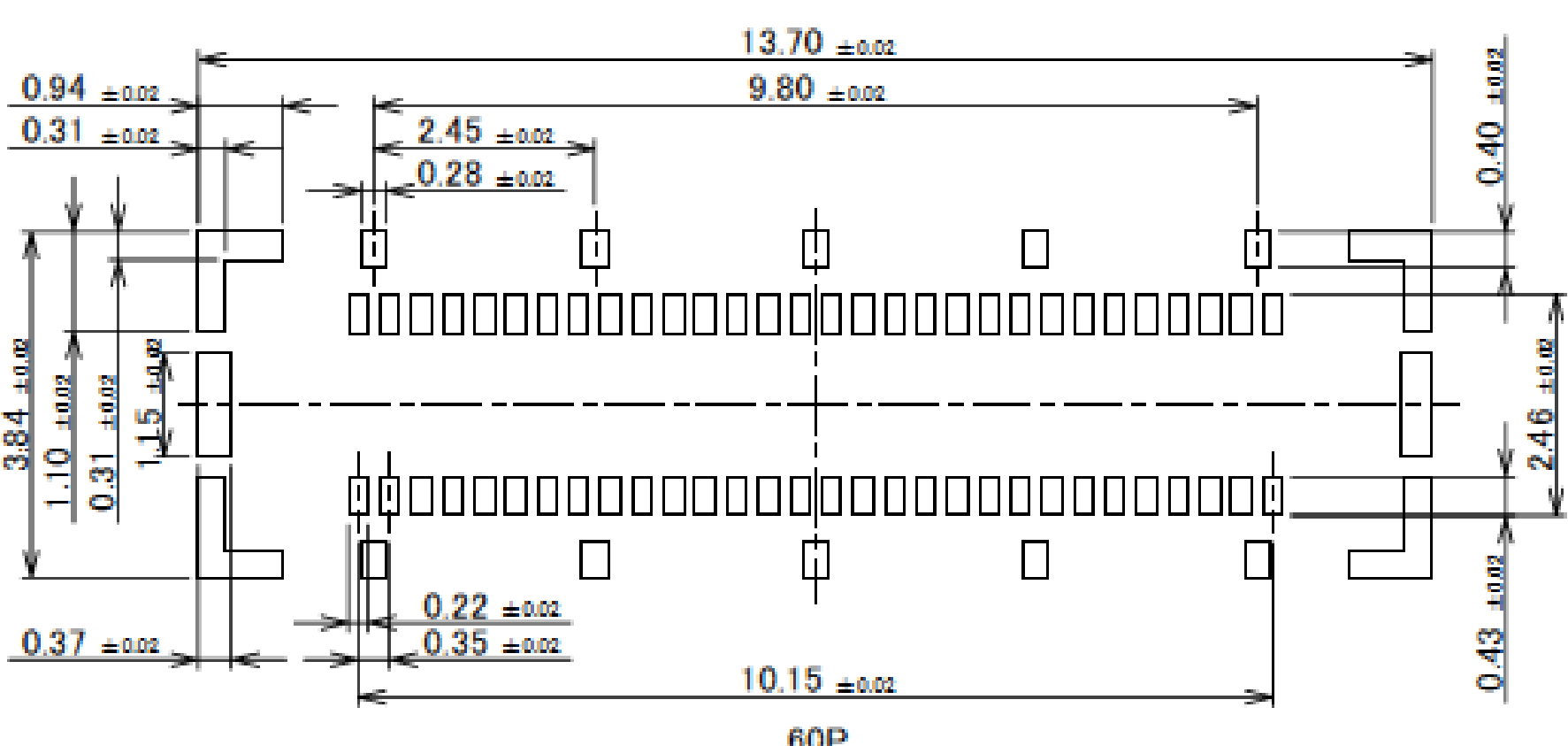
3	SHELL	CORSON ALLOY	ALL Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
2	CONTACT	CORSON ALLOY	CONTACT AREA: Au 0.13 μ m MIN. OVER Ni 1.27 μ m MIN. SOLDERING AREA: Au 0.02 μ m MIN. OVER Ni 1.27 μ m MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DESCRIPTION	MATERIAL	FINISH , REMARKS

Plug Assembly

RECOMMENDED PATTERN LAYOUT

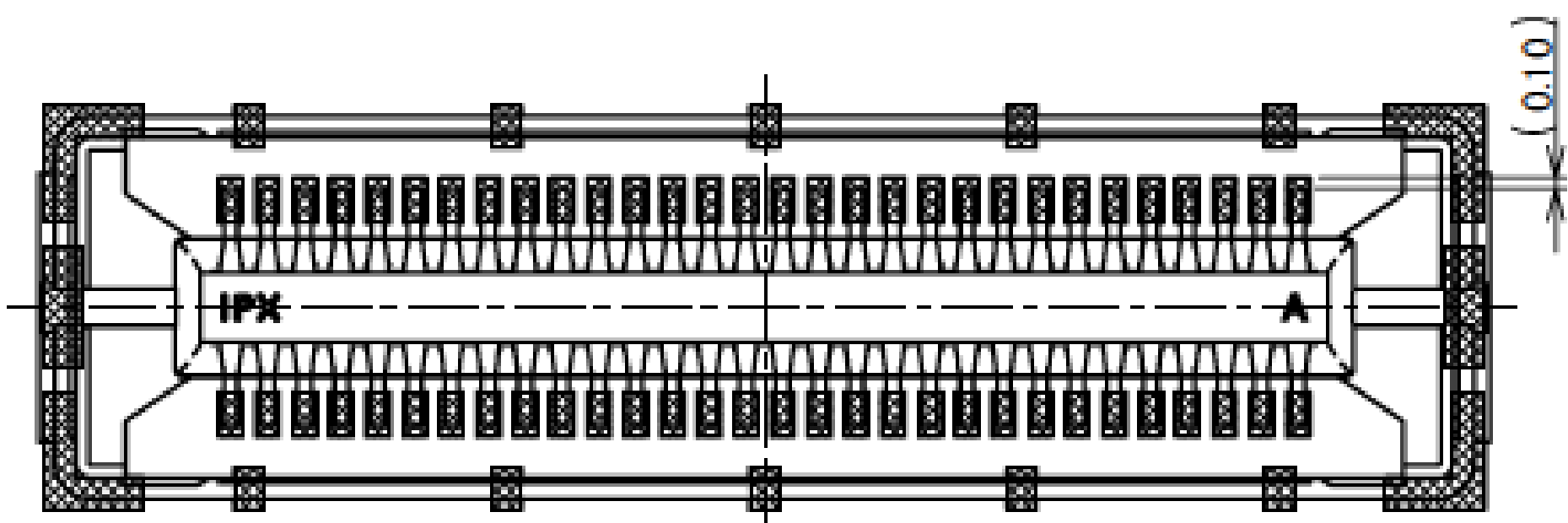


RECOMMENDED METAL MASK LAYOUT (t=0.10)

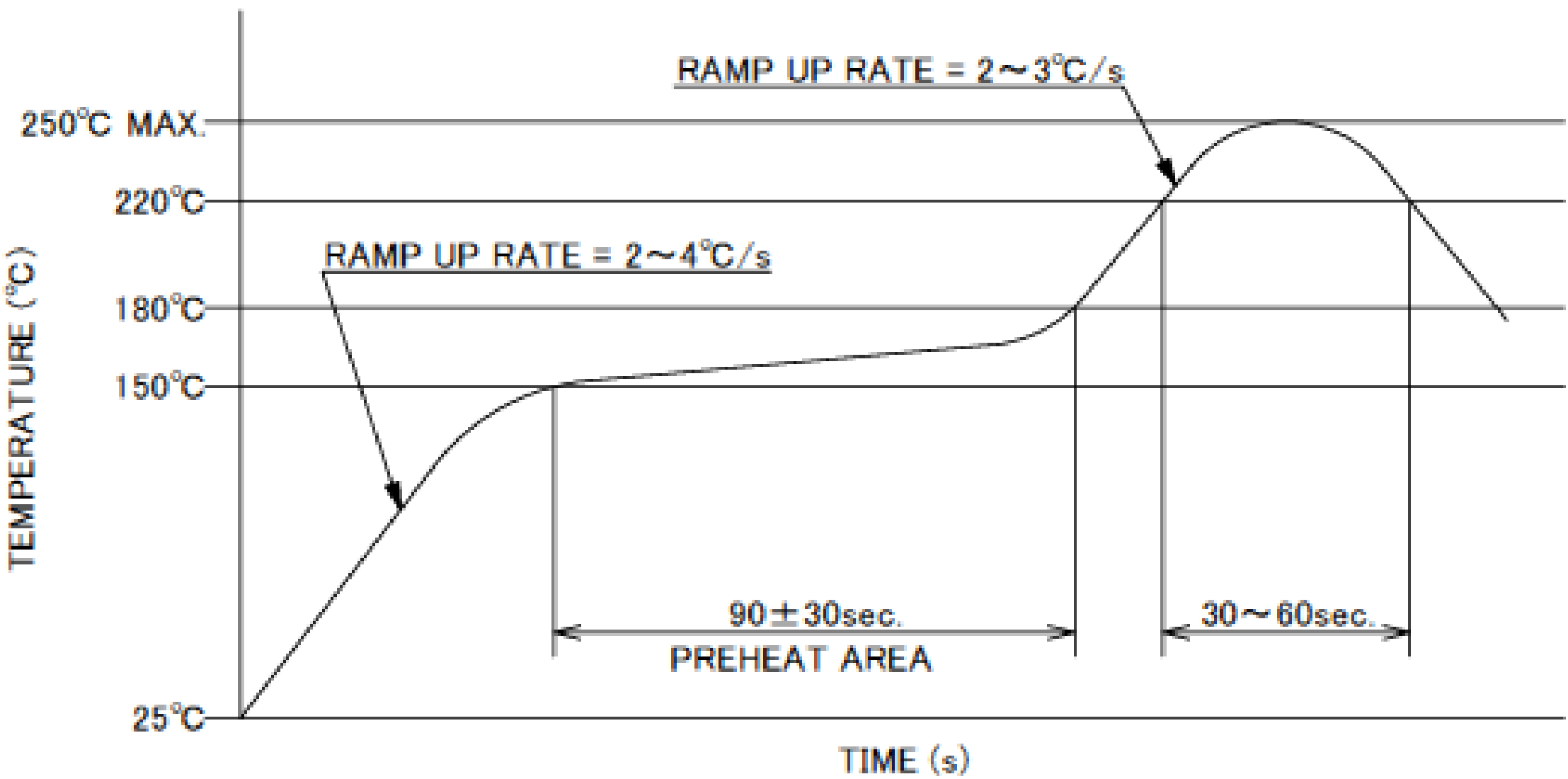


PART No.	Pos.	C
21003-060E	60	13.90
21003-070E	70	15.65

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CONNECTOR ON RECOMMENDED FOOT PRINT PATTERN LAYOUT



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.3

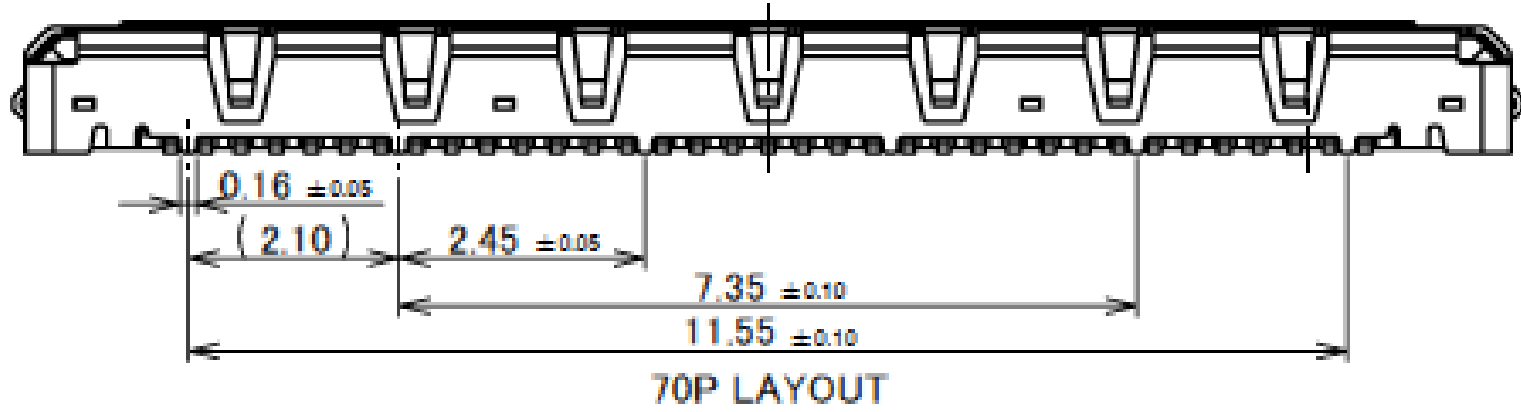
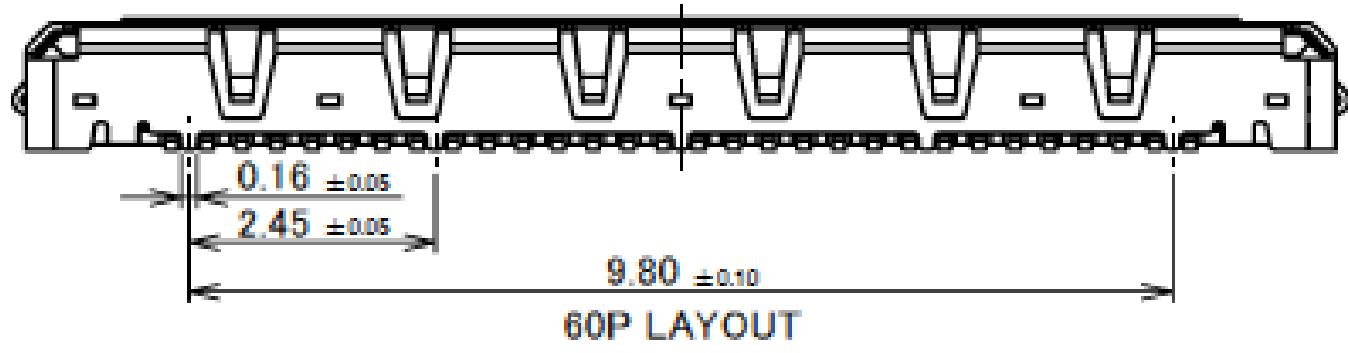
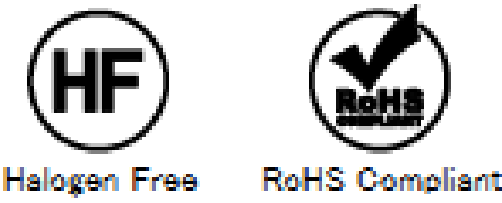
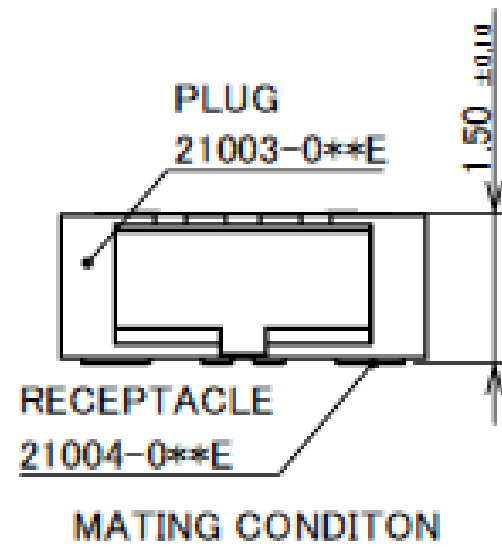
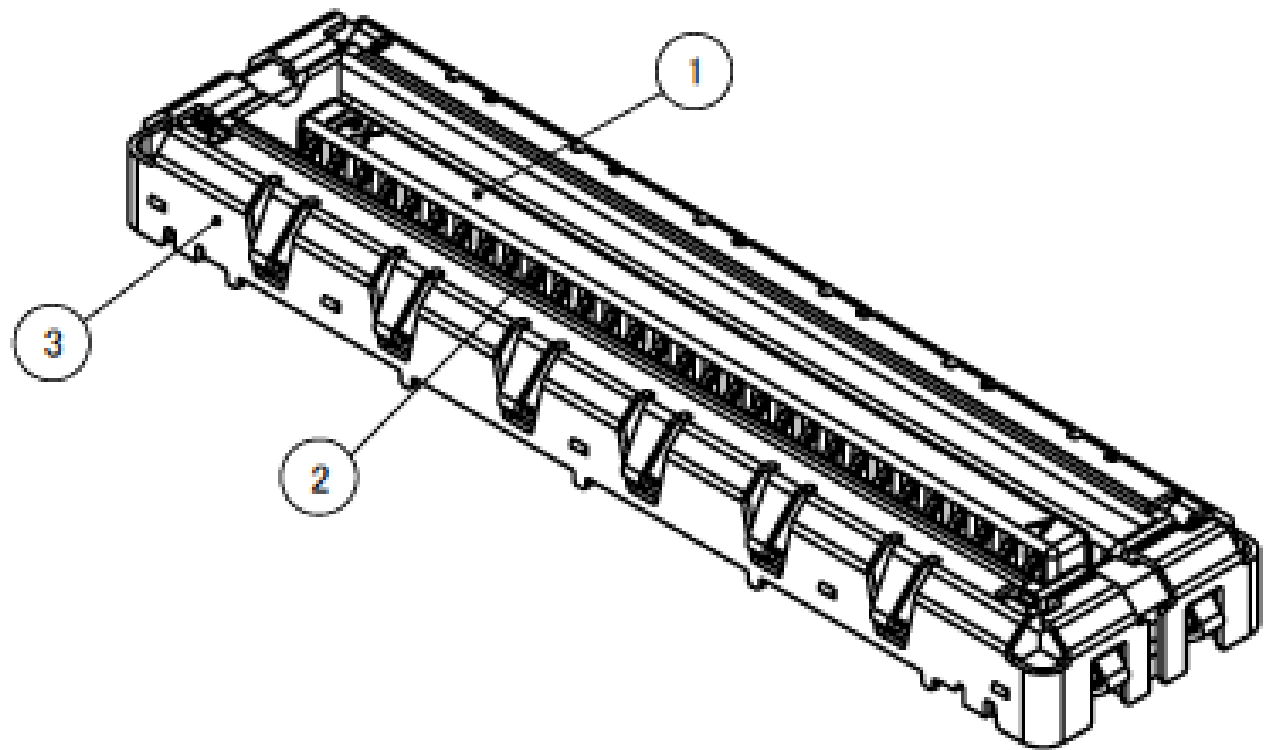
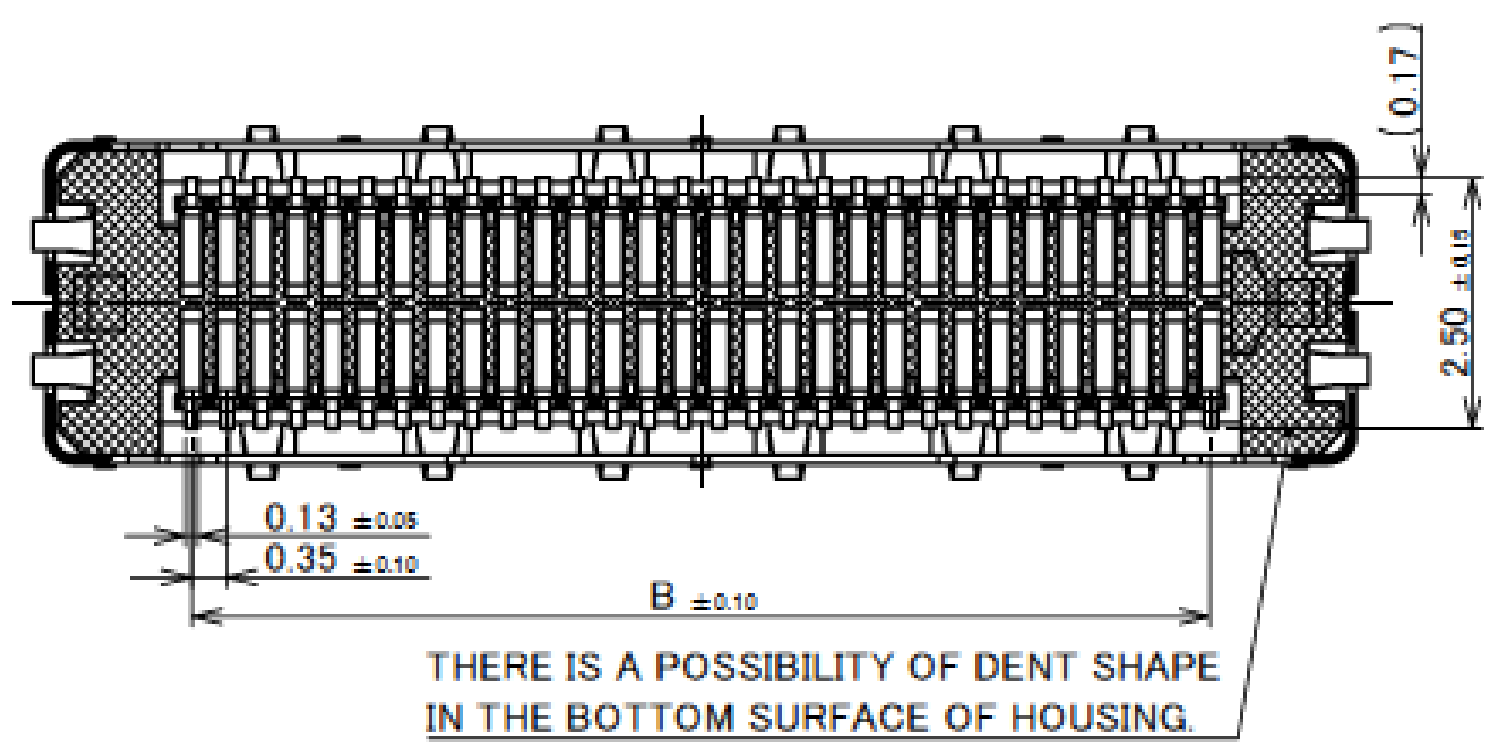
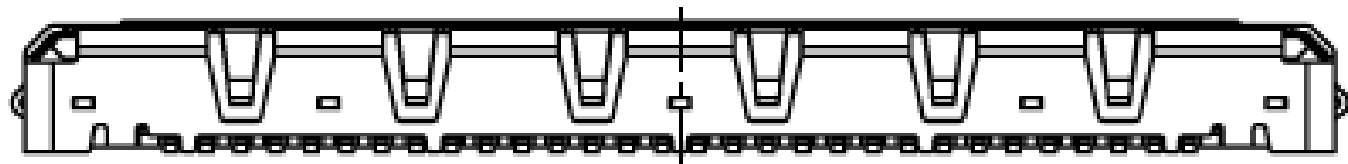
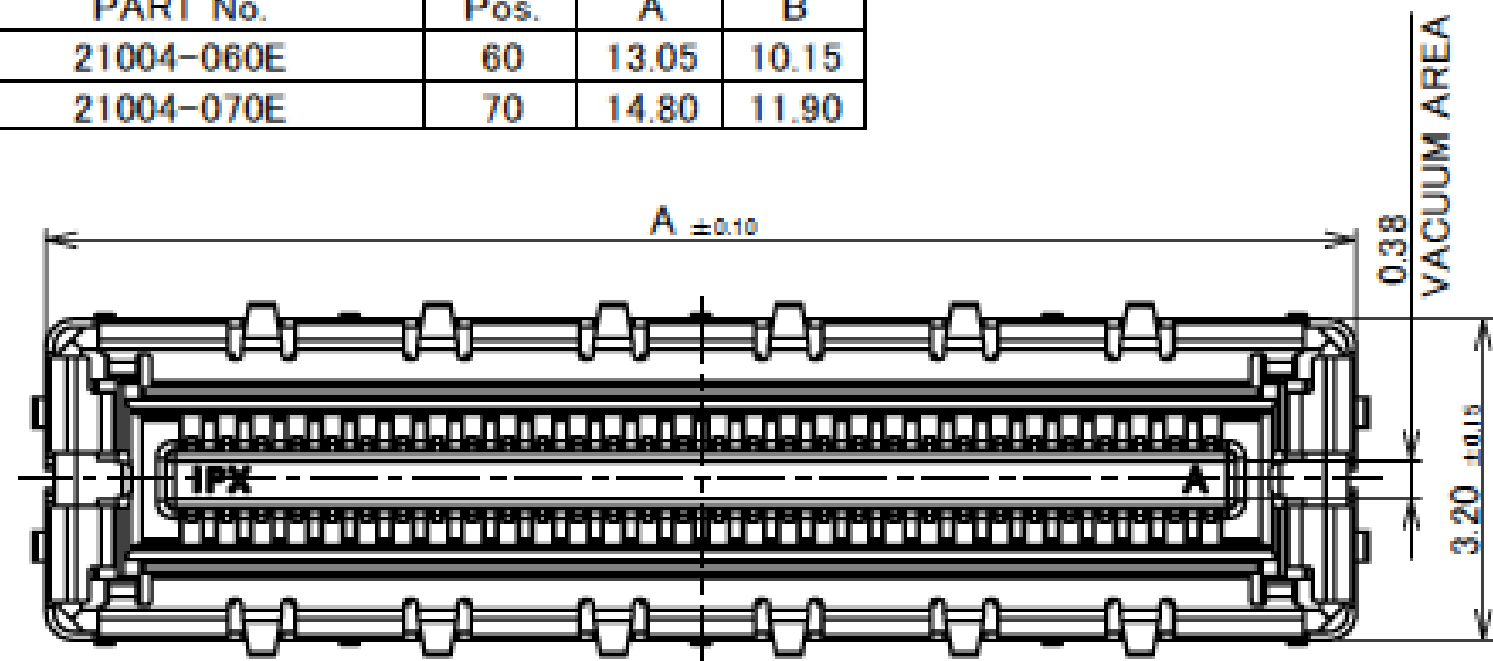
Plug Assembly

ITEMS	SPECIFICATION
APPLICABLE CONNECTOR PART No.	21004-0**E
RATING VOLTAGE	60V AC (R.M.S.)/DC (PER CONTACT PIN)
RATING AMPERAGE (FOR SIGNAL CONTACT)	0.5A AC/DC (PER CONTACT PIN)/ 12.0A AC/DC(TOTAL)
OPERATING TEMPERATURE	233~358K(-40℃~+85℃) (CONTANING TEMPERATURE RISE BY CURRENT)
OPERATING HUMIDITY	85% MAX.
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 50mohm MAX. / AFTER TEST : $\triangle$ 50mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : $\triangle$ 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	20 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 60P: 60N MAX. 70P: 70N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	20 CYCLES 60P: 6.0N MIN. 70P: 7.0N MIN.
COPLANARITY	0.10mm MAX.
PRODUCT SPECIFICATION	PRS-2785
TEST REPORT	TR-22021
PACKING STANDARD	PST-21086
INSTRUCTION MANUAL	HIM-21015
APPEARANCE CRITERIA No.	QLS-A***

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Receptacle Assembly

Recommended P/N	21004-0**E		
PART No.	Pos.	A	B
21004-060E	60	13.05	10.15
21004-070E	70	14.80	11.90

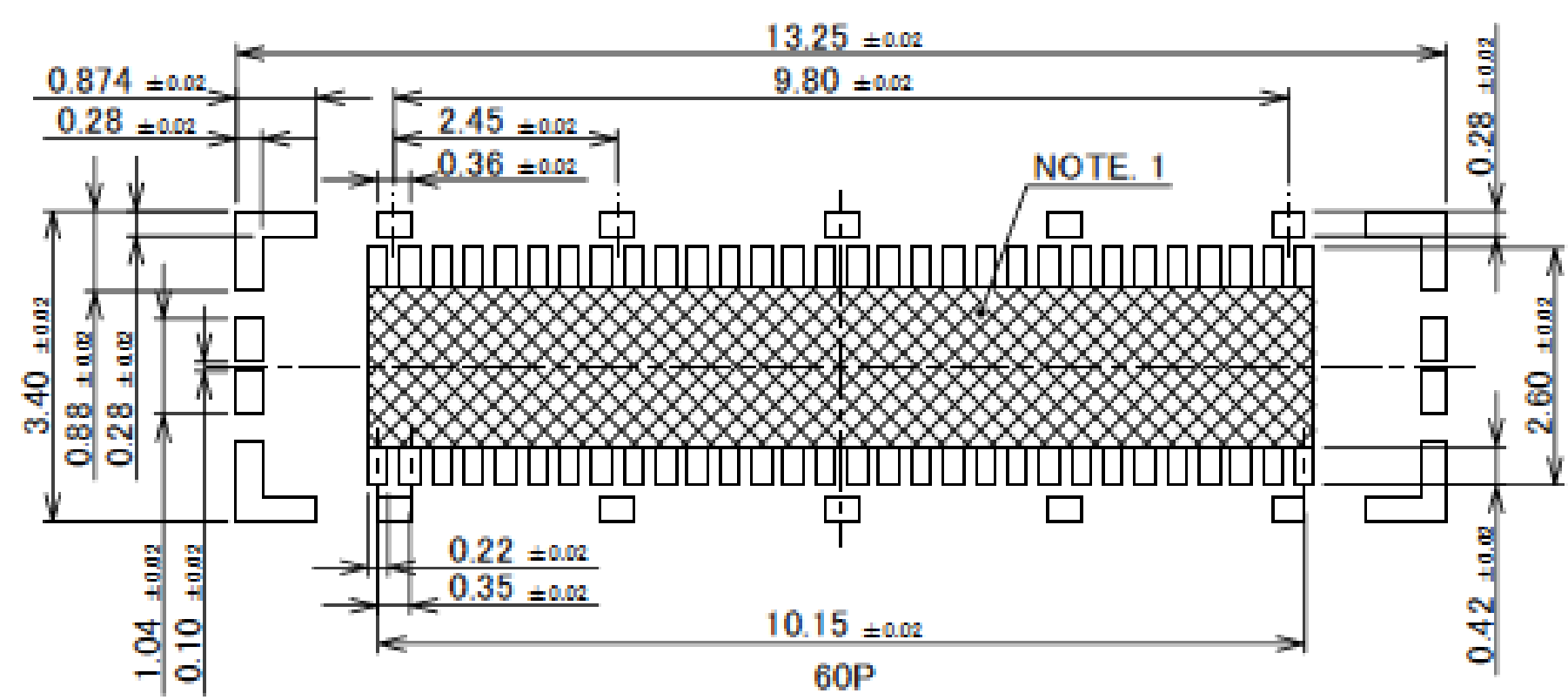


3	SHELL	CORSON ALLOY	ALL Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
2	CONTACT	CORSON ALLOY	CONTACT AREA: Au 0.13 μ m MIN. OVER Ni 1.27 μ m MIN. SOLDERING AREA: Au 0.02 μ m MIN. OVER Ni 1.27 μ m MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DESCRIPTION	MATERIAL	FINISH , REMARKS

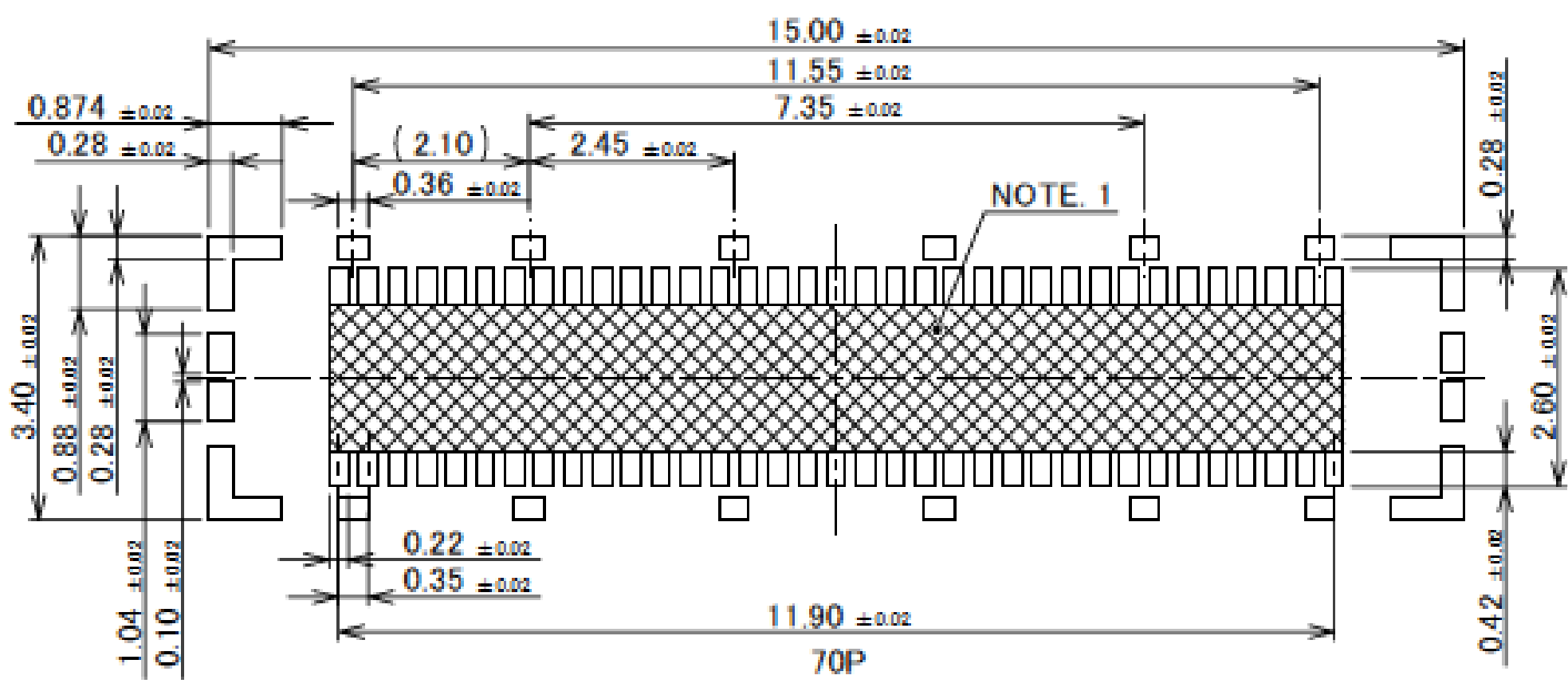
Rev.3

Receptacle Assembly

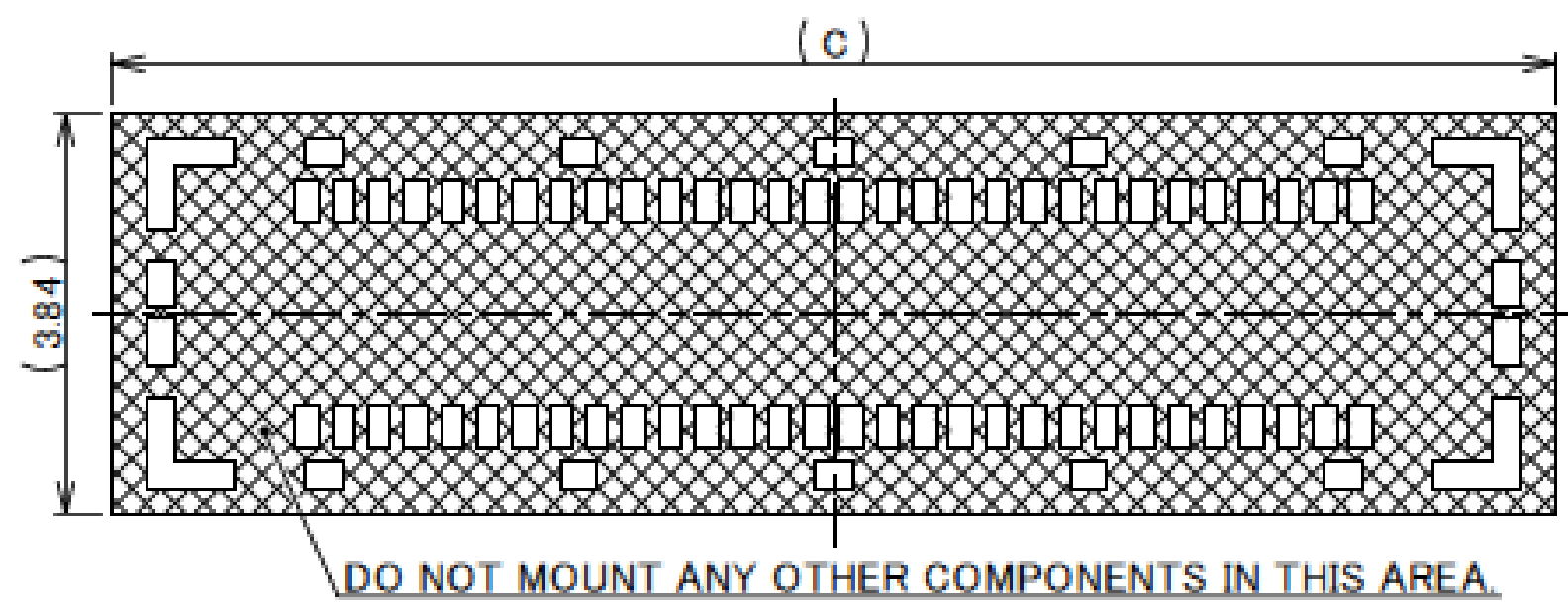
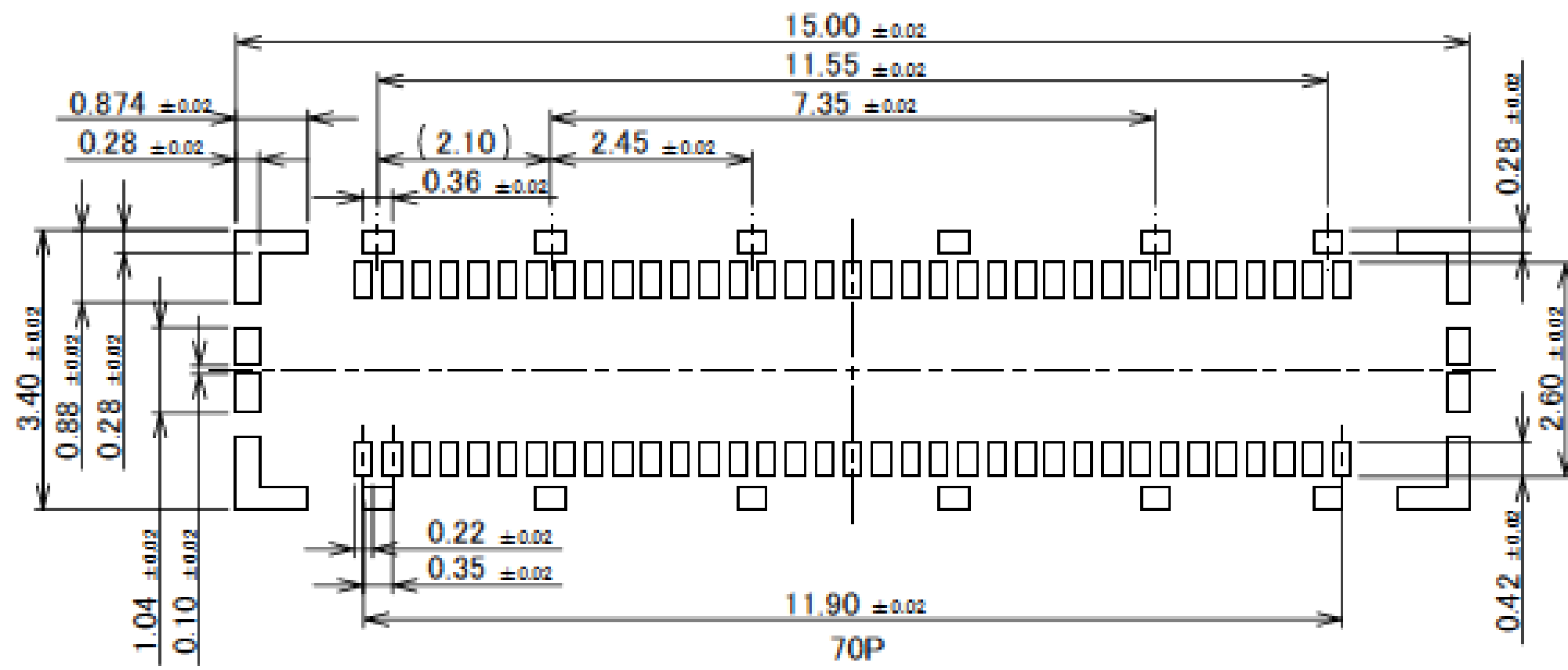
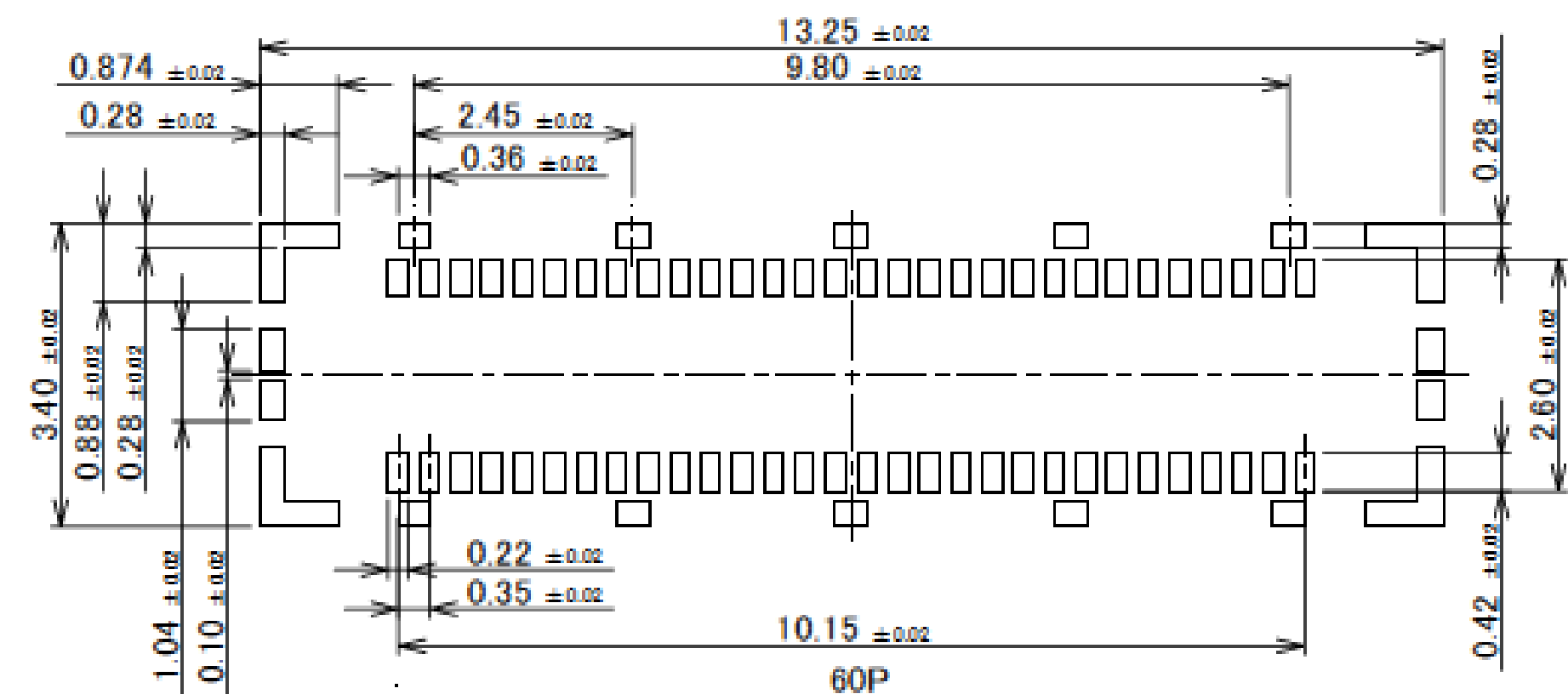
RECOMMENDED PATTERN LAYOUT



NOTES.
1. FOOT PRINT PATTERN PROHIBITION AREA
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA IF SURFACE TRACES ARE ROUNDED.

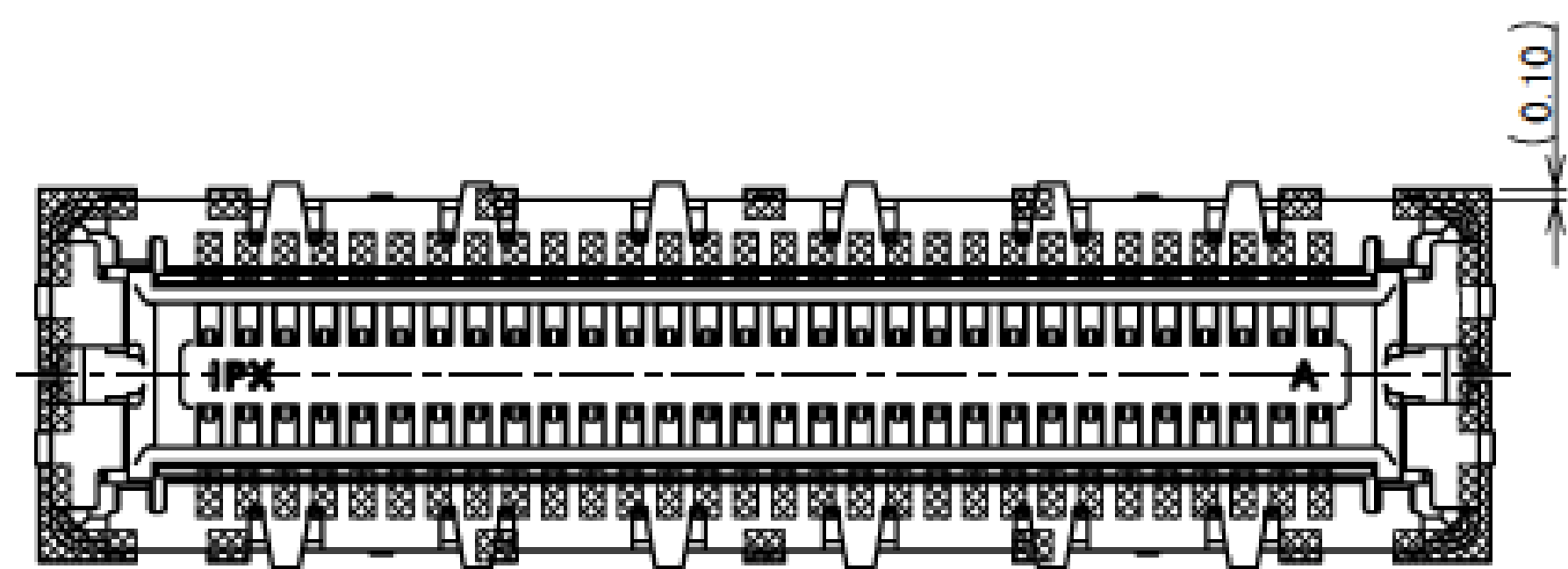


RECOMMENDED METAL MASK LAYOUT (t=0.10)

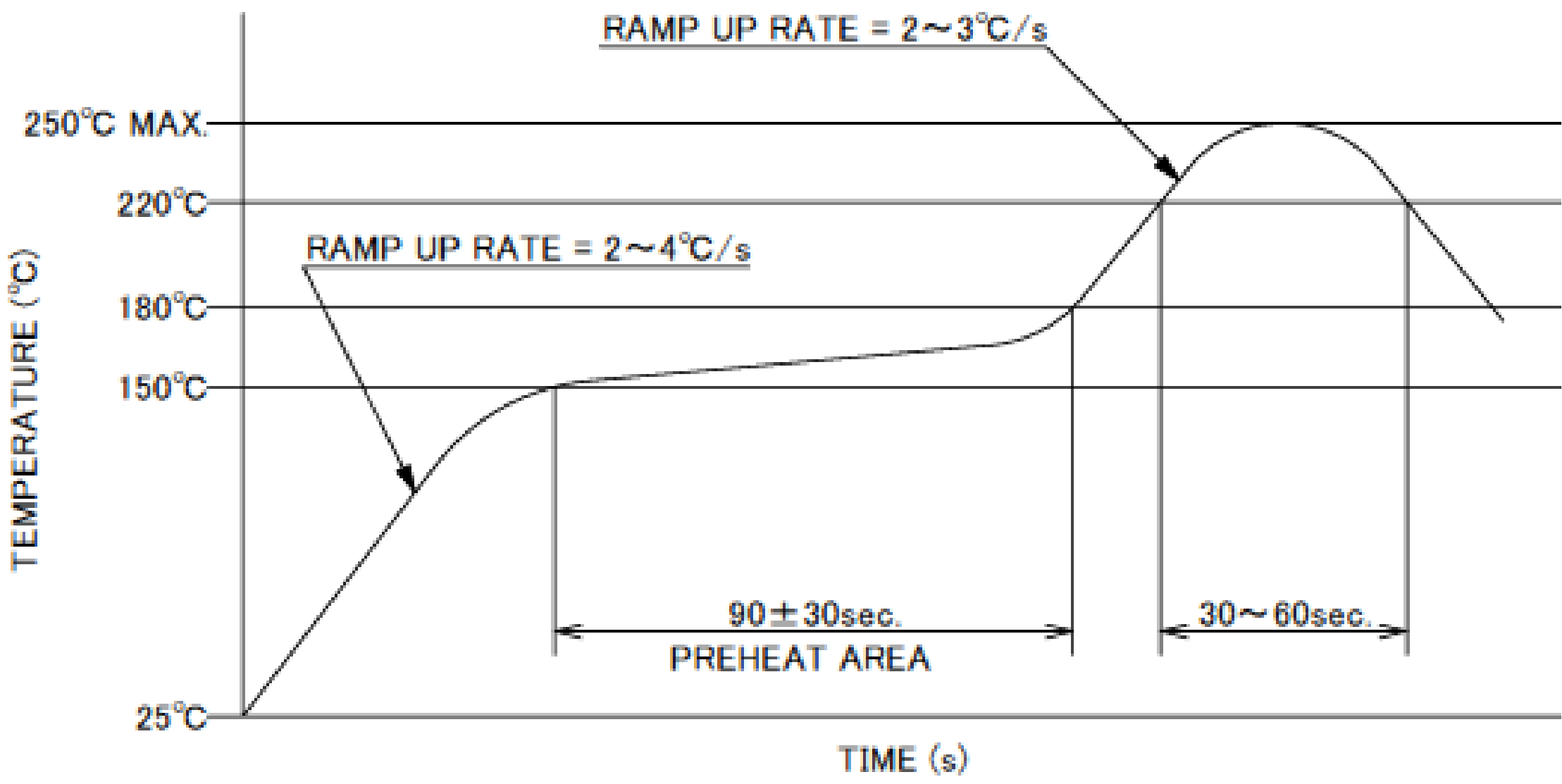


PART No.	Pos.	C
21004-060E	60	13.90
21004-070E	70	15.65

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CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN LAYOUT



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Receptacle Assembly

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APPLICABLE CONNECTOR PART No.	21003-0**E
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RATING AMPERAGE (FOR SIGNAL CONTACT)	0.5A AC/DC (PER CONTACT PIN)/ 12.0A AC/DC(TOTAL)
OPERATING TEMPERATURE	233~358K(-40℃~+85℃) (CONTANING TEMPERATURE RISE BY CURRENT)
OPERATING HUMIDITY	85% MAX.
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 50mohm MAX. / AFTER TEST : $\triangle$ 50mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : $\triangle$ 20mohm MAX.
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DURABILITY	20 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 60P: 60N MAX. 70P: 70N MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	20 CYCLES 60P: 6.0N MIN. 70P: 7.0N MIN.
COPLANARITY	0.10mm MAX.
PRODUCT SPECIFICATION	PRS-2785
TEST REPORT	TR-22021
PACKING STANDARD	PST-21087
INSTRUCTION MANUAL	HIM-21015
APPEARANCE CRITERIA No.	QLS-A***

Rev.3

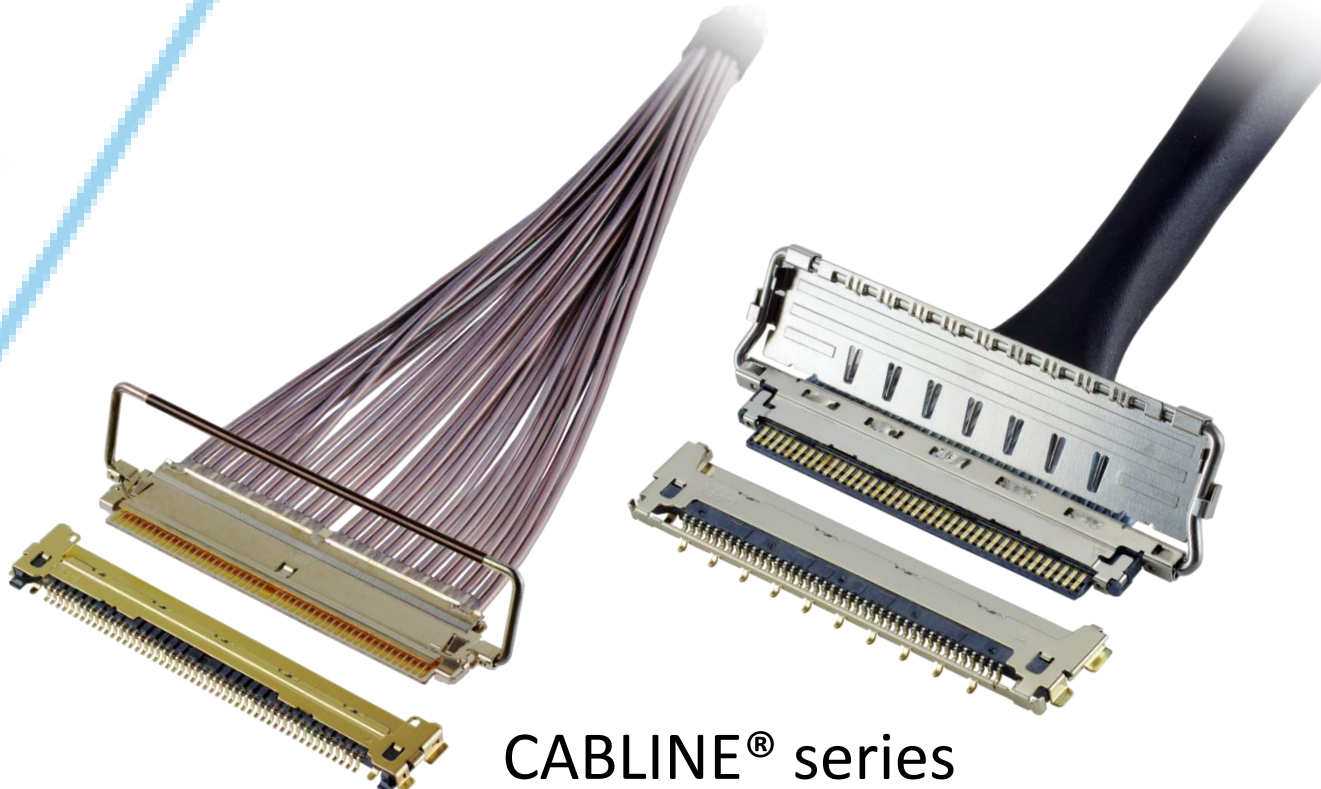
Custom Connectors Available

 RF
Connectors

MHF® series



CABLINE® series

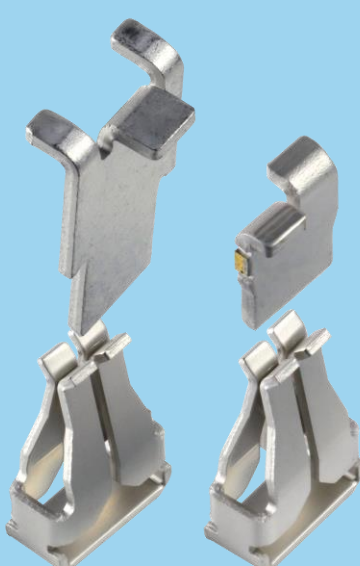


Micro-coaxial/Twinax
Connectors

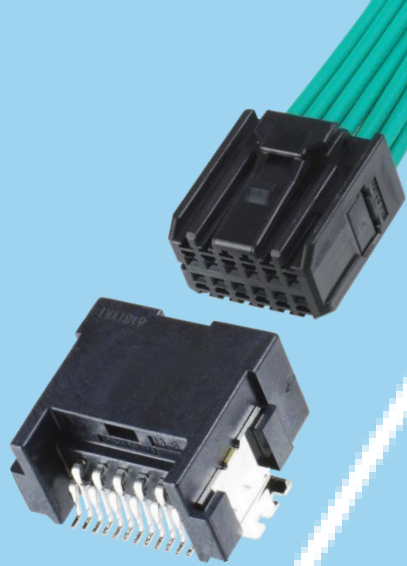


Wire-to-Board
Connectors/
Terminals

AP series



ISH® series



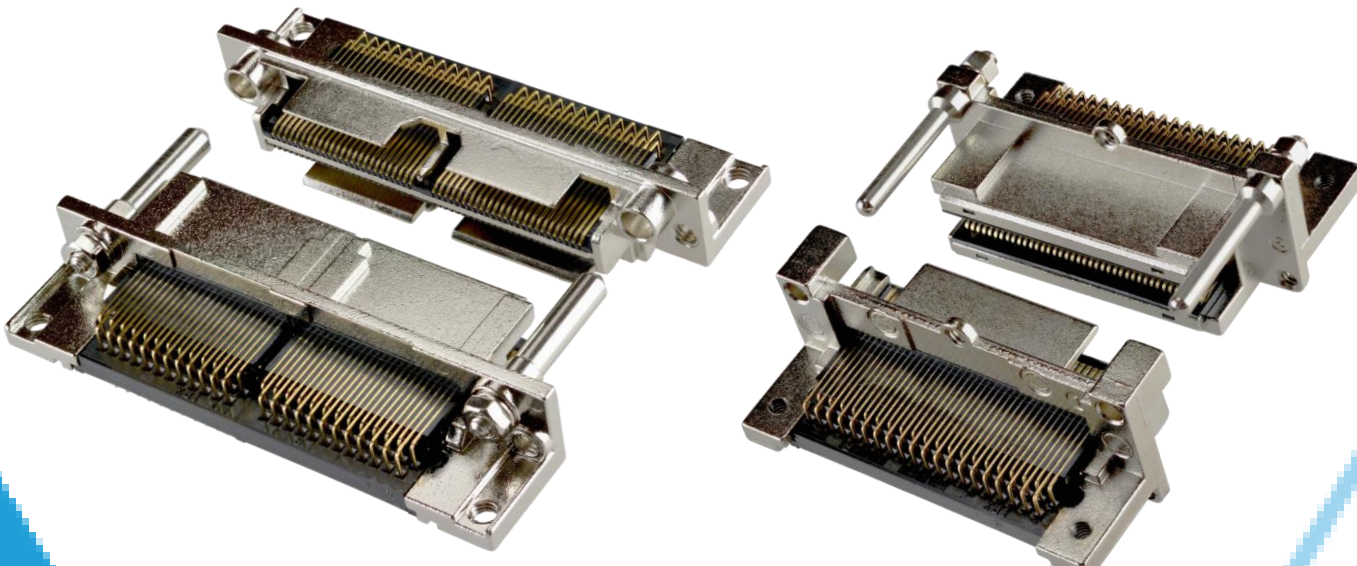
NOVASTACK® series



Board-to-Board
Connectors



I/O
Connectors



MINIDOCK™ series

MINIFLEX® series

EVAFLEX® series



FPC/FFC
Connectors



Inquiry



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